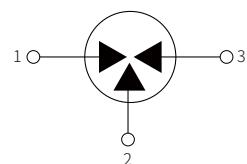


## FEATURES

- | Size Design 6.0\*6.0\*8.0mm
- | High Current Handling Capability 20,000A @ 8/20  $\mu$ s
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



6.0\*6.0\*8.0mm



Schematic Symbol

## APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free
UL	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage <sup>1)</sup>	100V/s	184-276	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values $\leq 700$	V
	At 1kV/μs	Typical values of distribution $\leq 650$	V
Impulse Discharge Current <sup>2)</sup>	8/20μs	20	KA
Insulation Resistance	DC=100V	$\geq 1$	GΩ
Capacitance at 1MHz	$V_{DC}=0.5V$	$\leq 1.5$	pF
Operating and Storage Temperature		-40~125	°C

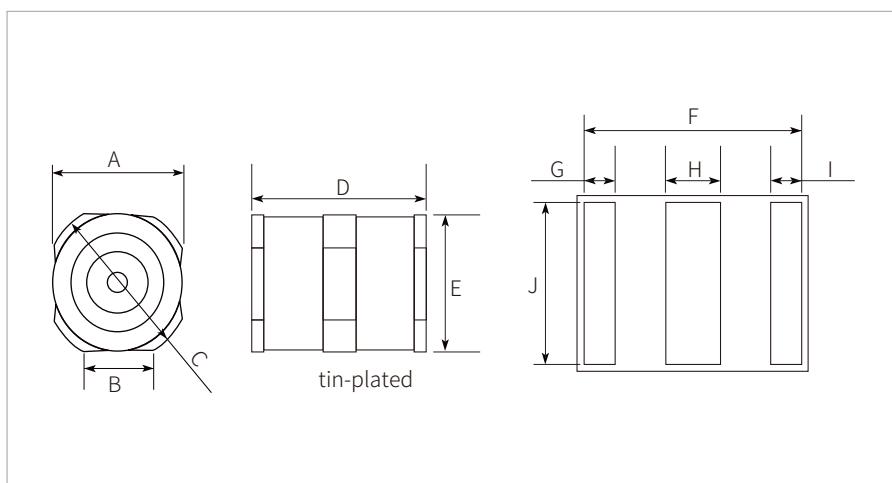
1) In ionized mode

2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude 0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260°C; Time of dip soldering 10s,1time

## PRODUCT DIMENSIONS



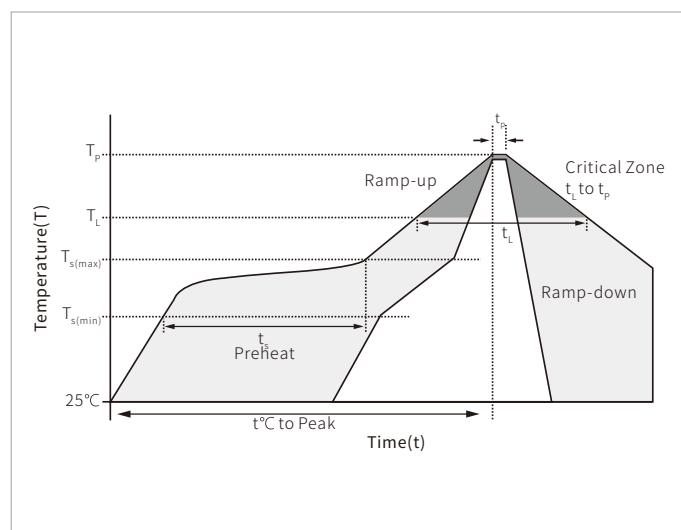
Ref.	Outline Dimensions
	Millimeters
A	6.0±0.2
B	3.2
C	Φ6.8
D	8.2±0.3
E	Φ6.0±0.1
F	8.8
G	1.2
H	2.2
I	1.2
J	6

## SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4~6 seconds

## REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60~180 secs
Average ramp up rate (Liquidus)Temp $T_L$ to peak		
$T_s(\text{max})$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time(min to max)( $t$ )	60~150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t$ )		20~40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C



## ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG3R06B230C	6.0*6.0*8.0mm	SG3R06 B230	600PCS	13 "

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**By QR Code**

Website



Wechat

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